

SN54AHCT367, SN74AHCT367 HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS418E – JUNE 1998 – REVISED JUNE 2000

- **EPIC™** (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- True Outputs
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages, Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs

description

The 'AHCT367 devices are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices are organized as dual 4-line and 2-line buffers/drivers with active-low output-enable ($1\overline{OE}$ and $2\overline{OE}$) inputs. When \overline{OE} is low, the device passes noninverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

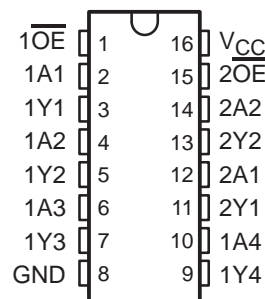
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHCT367 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AHCT367 is characterized for operation from -40°C to 85°C .

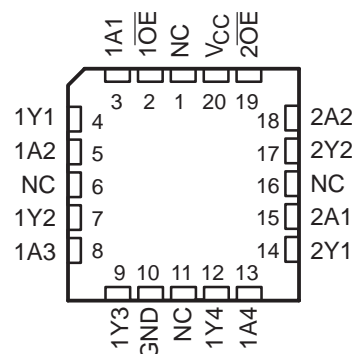
FUNCTION TABLE
(each buffer/driver)

INPUTS		OUTPUT
\overline{OE}	A	Y
H	X	Z
L	H	H
L	L	L

SN54AHCT367 . . . J OR W PACKAGE
SN74AHCT367 . . . D, DB, DGV, N, OR PW PACKAGE
(TOP VIEW)



SN54AHCT367 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



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**TEXAS
INSTRUMENTS**

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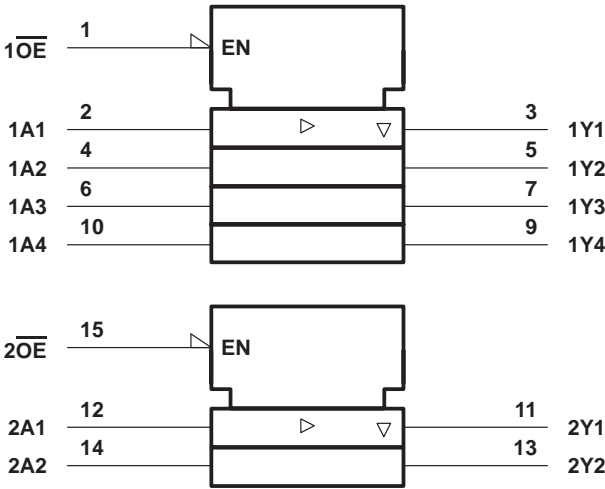
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HEX BUFFERS AND LINE DRIVERS

WITH 3-STATE OUTPUTS

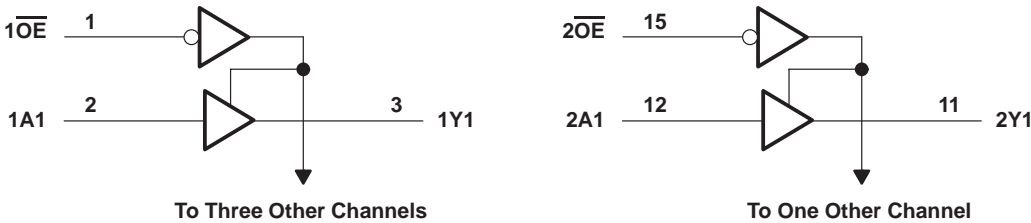
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, DGV, J, N, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±75 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
N package	67°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

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recommended operating conditions (see Note 3)

		SN54AHCT367		SN74AHCT367		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–8		–8	mA
I_{OL}	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		20		20	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			SN54AHCT367		SN74AHCT367		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$I_{OH} = -50\ \mu\text{A}$	4.5 V	4.4	4.5		4.4		4.4		V
	$I_{OH} = -8\ \text{mA}$		3.94			3.8		3.8		
V_{OL}	$I_{OL} = 50\ \mu\text{A}$	4.5 V			0.1	0.1		0.1		V
	$I_{OL} = 8\ \text{mA}$				0.36	0.44		0.44		
I_I	$V_I = V_{CC}$ or GND	0 V to 5.5 V			$\pm 0.1^*$	$\pm 1^*$		± 1		μA
I_{OZ}	$V_I = V_{CC}$ or GND, $\overline{OE} = V_{IH}$	5.5 V			± 0.25	± 2.5		± 2.5		μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4	40		40		μA
ΔI_{CC}^\dagger	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			1.35	1.5		1.5		mA
C_i	$V_I = V_{CC}$ or GND	5 V		2.5	10	10		10		pF
C_o	$V_O = V_{CC}$ or GND	5 V		5						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0\ \text{V}$.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC} .

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHCT367		SN74AHCT367		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	$C_L = 15\text{ pF}$	2.5*	4.8*		1*	6.5*	1	5.5	ns
t_{PHL}				2.5*	4.8*		1*	6.5*	1	5.5	
t_{PZH}	\overline{OE}	Y	$C_L = 15\text{ pF}$	3.5*	8*		1*	9.5*	1	8.5	ns
t_{PZL}				2.8*	7*		1*	8.5*	1	7.5	
t_{PHZ}	\overline{OE}	Y	$C_L = 15\text{ pF}$	3.1*	8*		1*	9.5*	1	8.5	ns
t_{PLZ}				2.8*	7*		1*	8.5*	1	7.5	
t_{PLH}	A	Y	$C_L = 50\text{ pF}$	3.5	5.8		1	7.5	1	6.5	ns
t_{PHL}				3.3	5.8		1	7.5	1	6.5	
t_{PZH}	\overline{OE}	Y	$C_L = 50\text{ pF}$	4.5	9		1	10.5	1	9.5	ns
t_{PZL}				3.7	8		1	9.5	1	8.5	
t_{PHZ}	OE	Y	$C_L = 50\text{ pF}$	4.1	9		1	10.5	1	9.5	ns
t_{PLZ}				3.6	8		1	9.5	1	8.5	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER		SN74AHCT367			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.4		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.4		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.7		V
$V_{IH(D)}$	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

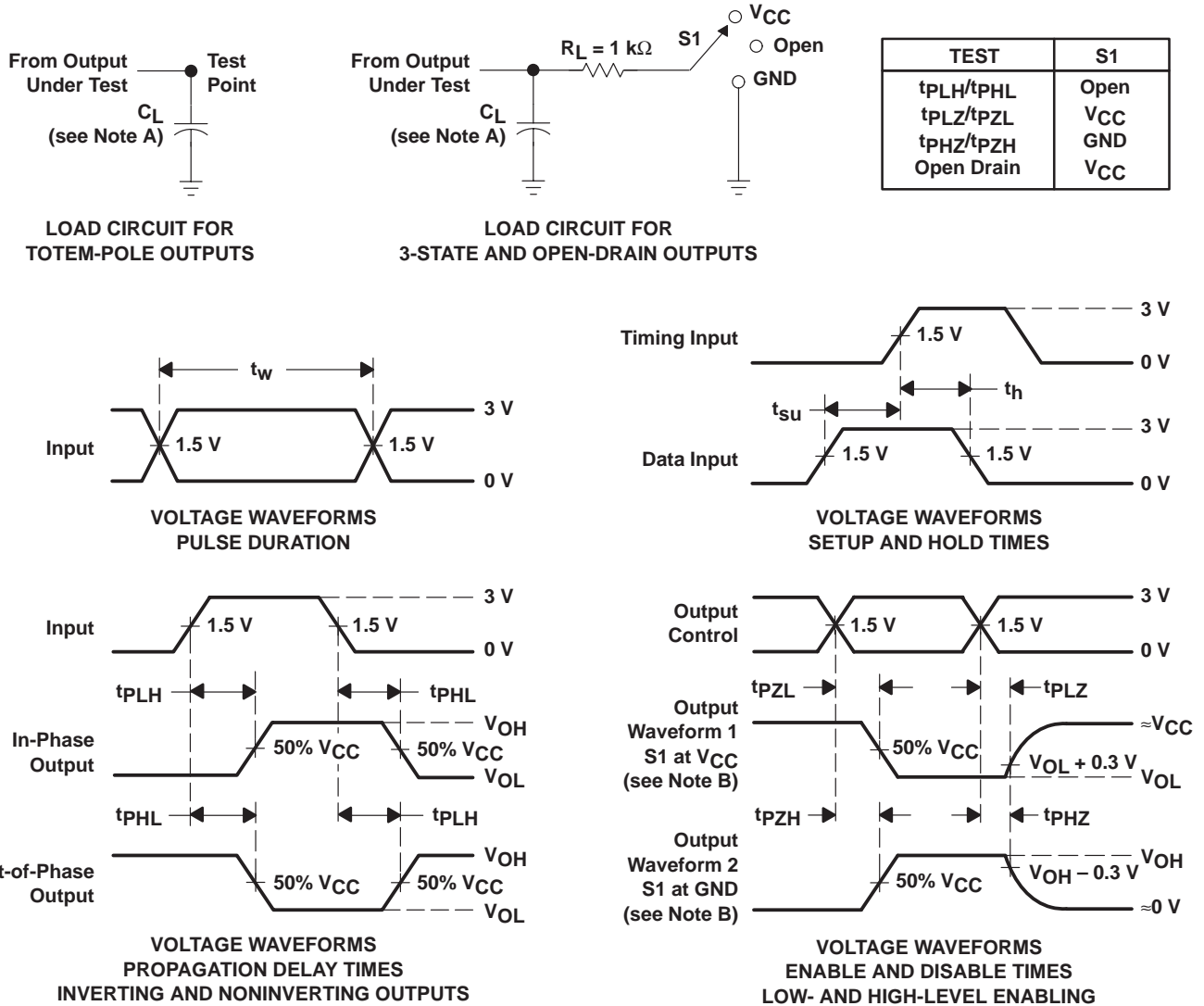
PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	22	pF

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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